

METHOD AND DEVICE OF PEELING SEMICONDUCTOR DEVICE USING  
ANNULAR CONTACT MEMBERS

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ABSTRACT OF THE DISCLOSURE

10 In a semiconductor device manufacturing process, a  
semiconductor wafer is diced into a plurality of  
semiconductor chips, which are then peeled, from a  
dicing tape, using a peeling device. The peeling device  
includes a plurality of annular contact members arranged  
one after another from the outside to the inside, and  
15 the annular contact members are operated so that the  
semiconductor chip is successively peeled from the tape  
from the outer circumferential portion thereof toward  
the central portion thereof.

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